

Near-Field Scanning

Searching for Root Causes



Outline

- Emission Scanning
 - Sniffer probes are smarter than they look
 - Electromagnetic lens: from near-field to far-field
- Susceptibility Scanning
 - Conducted susceptibility: where does ESD current go?
 - Near-field effects of electrostatic discharge events



Emission Scanning



Sniffer Probe





EMI Near-Field Probe

EMI Probes:

- Up to 40 GHz
- Down to 50 kHz

Optional EMI Probes;

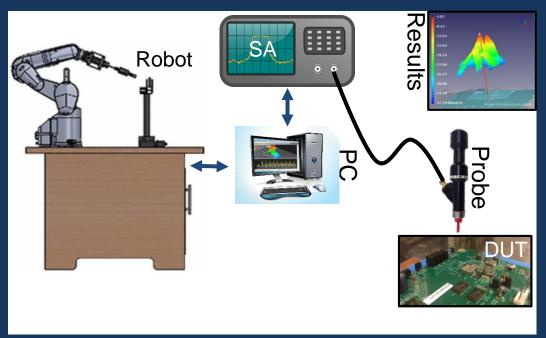
Choose:

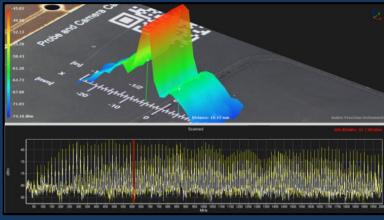
- Size
- Frequency range
- Field Component





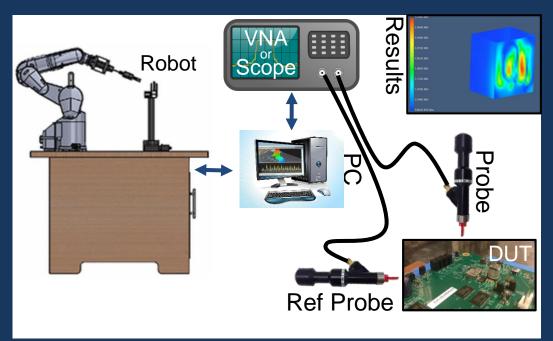
EMI Near-Field Scanning

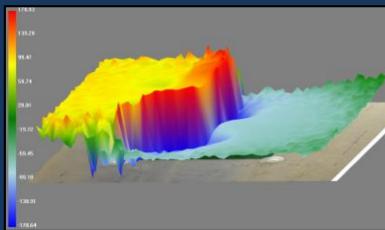






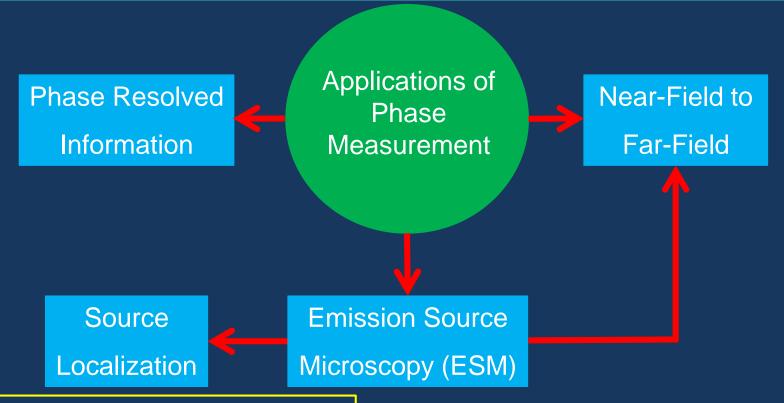
Phase Measurement Scanning







Applications of Phase Measurement

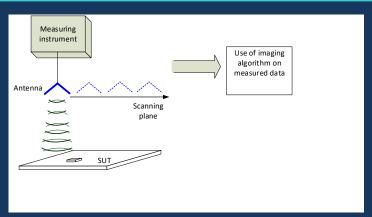


Applications of ESM:

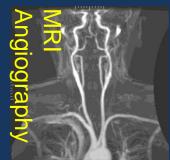
- High speed data communication
- Data centers, servers, routers, cloud
- 5G mobile network
- Radar systems
- Phased arrays
- Electrically large structures



History of ESM: Synthetic Aperture Radar (SAR)







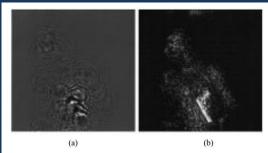
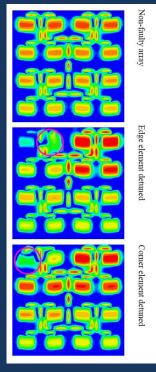


Fig. 5. (a) 35-GHz hologram and (b) reconstructed image of a mannequin carrying a concealed handgun.

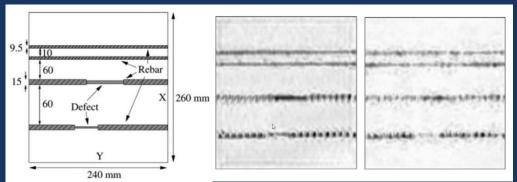


Fig. 6. 350-GHz reconstructed image of a Glock-17 9-mm handgun.



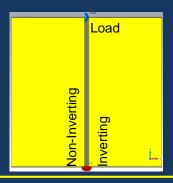
Applications of SAR:

- Airborne radar
- Medical imaging
- Concealed object detection
- Non-destructive testing
- Antenna diagnosis

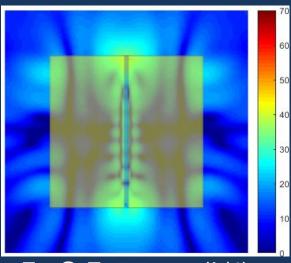




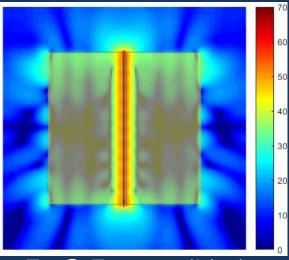
Symmetric Differential Microstrip



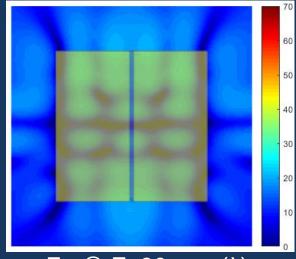
Full-wave simulation
Differential microstrip line
Differentially driven @ 10 GHz



Ex @ $Z=7.5 \text{ mm } (\lambda/4)$



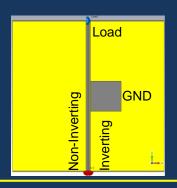
Ex @ Z=1 mm $(\lambda/30)$



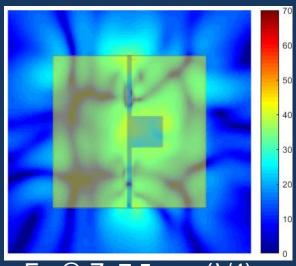
Ex @ $Z=30 \text{ mm } (\lambda)$



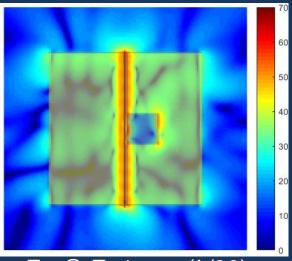
Asymmetric Differential Microstrip



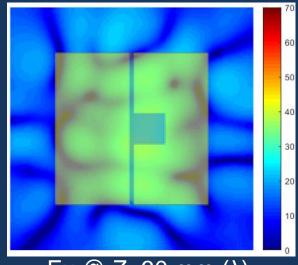
Asymmetric differential microstrip 12 mil gap between GND & line Differentially driven @ 10 GHz



Ex @ $Z=7.5 \text{ mm } (\lambda/4)$



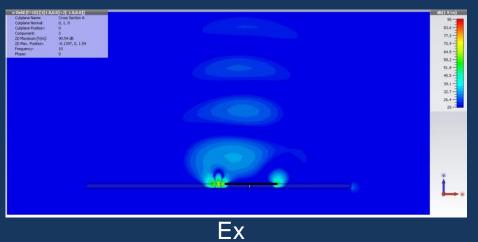
Ex @ Z=1 mm (λ/30)

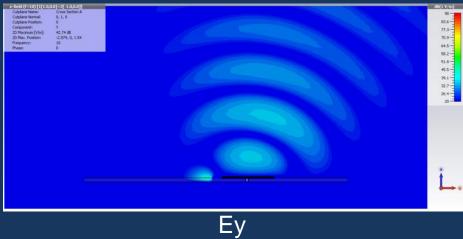


Ex @ Z=30 mm (λ)

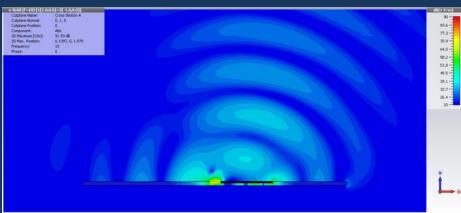


Wave Propagation





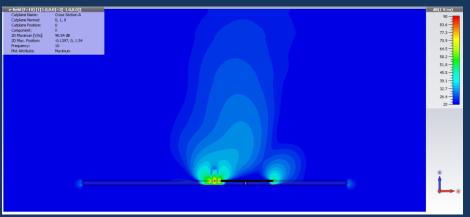
Confiden Name:
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Collaine Name:
Collai

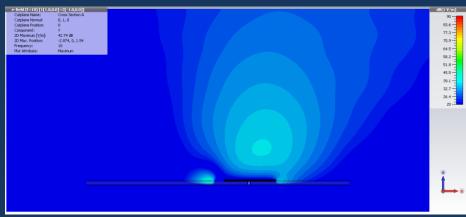


|E|

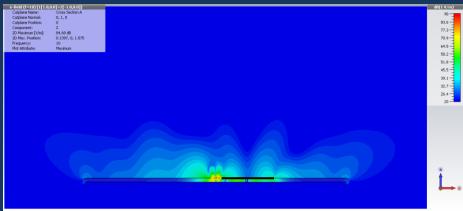


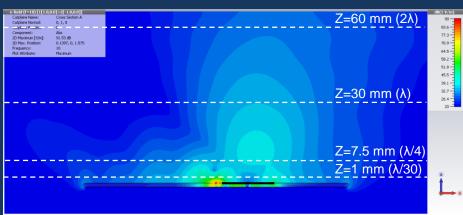
Wave Propagation





Max Ex Max Ey



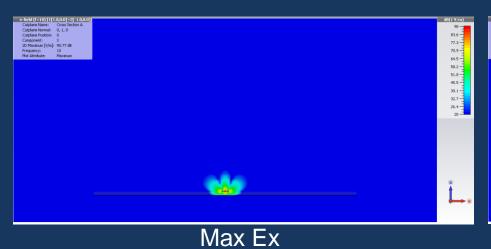


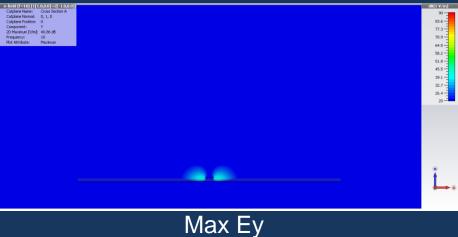
Max Ez Max |E|

12



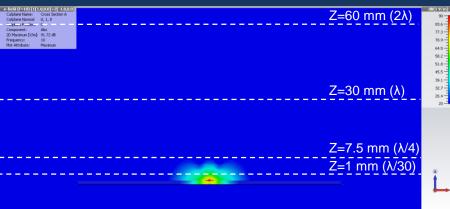
Wave Propagation





(m) (b / m)

(m



Max Ez Max |E|



Emission Source Microscopy (ESM)

$$f(x,y) = F_{2D}^{-1} \left\{ F_{2D} \left\{ s(x,y) e^{-jk_z z_0} \right\} \right\} \quad k_z = \sqrt{k^2 - k_x^2 - k_y^2}$$

Optional: Calculate Far-Field Pattern

Measure at Radiative Near-Field (~1-2λ away from DUT)

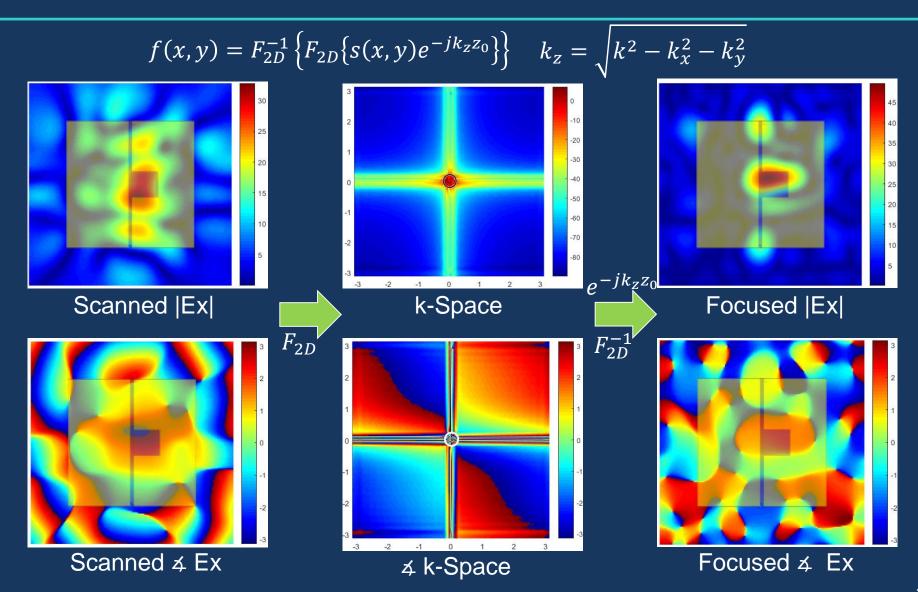
Back-Calculate to DUT Location (Phase Adjustment)*

Localize Sources
Contributing to
Far-Field

Optional: Calculate TRP

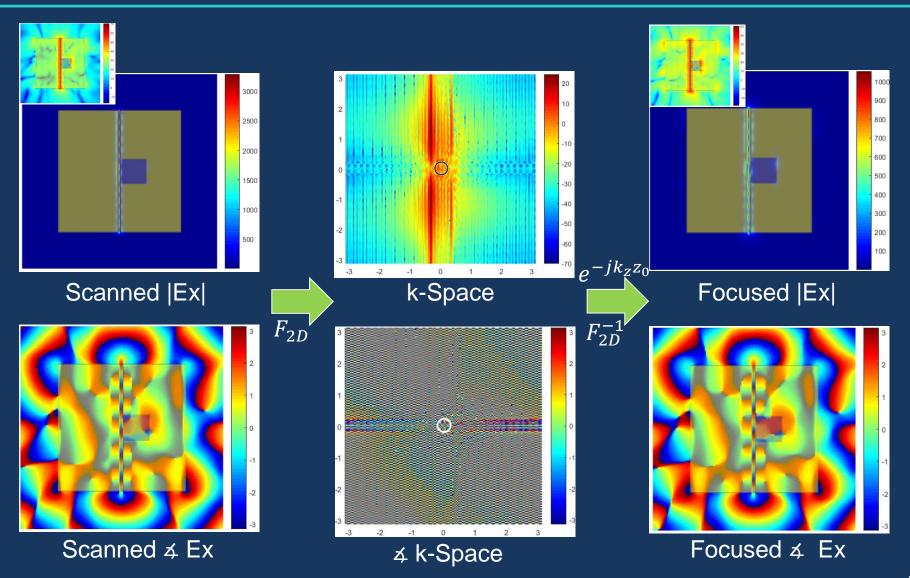


k-Space and Propagating Wave



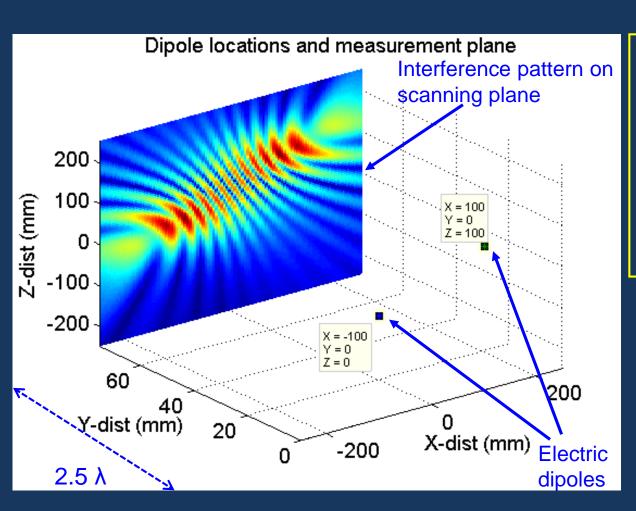


k-Space and Evanescent Wave





Ideal Dipole

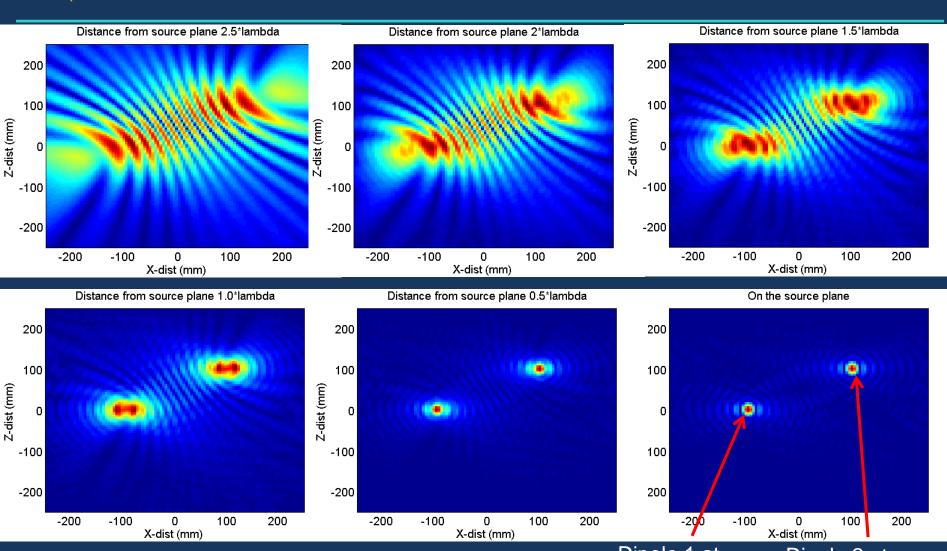


Two dipoles are placed Dipole 1 at (-100,0,0) mm, Dipole 2 at (100,0,100) mm

E fields components
Frequency = 10 GHz
Grid spacing = 0.5 mm
Distance = 2.5λ
Resolution ~ 15 mm



Focusing Lens at Different Distances



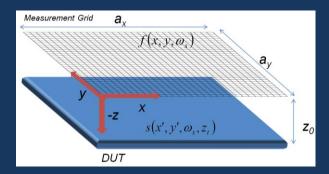
Correct location of dipoles is determined

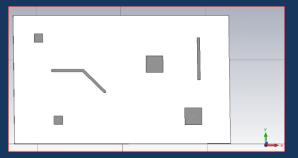
Dipole 1 at (-100,0,0) mm

Dipole 2 at (100,0,100) mm,



Applications of ESM



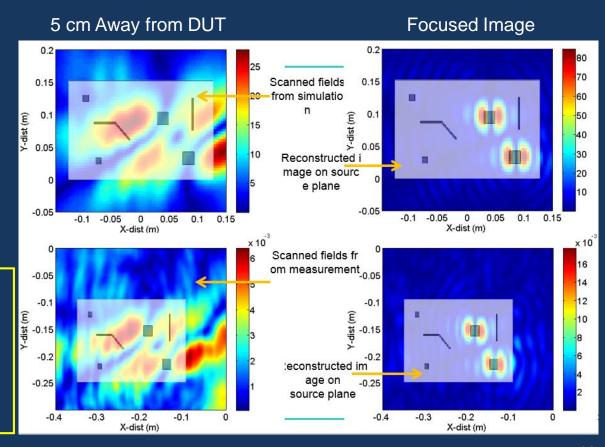


Measurement Setup:

- The measurement is performed at 8.2 GHz and at 5 cm away from DUT.
- Using VNA and open-ended waveguide used.

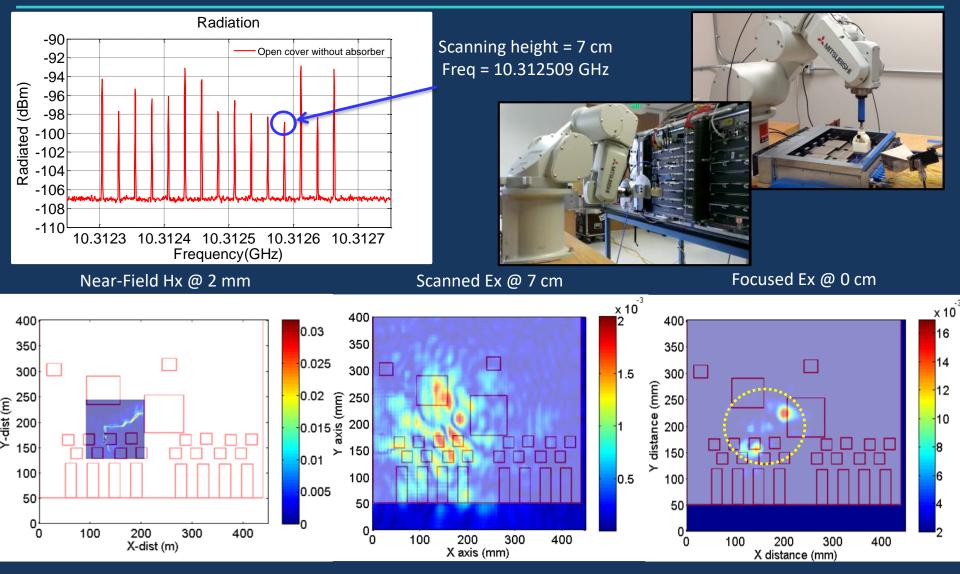
ESM Application of Synthetic Aperture Antenna (SAR) to EMC

- Identification of emission source
- FF estimation
- Total radiated power calculation



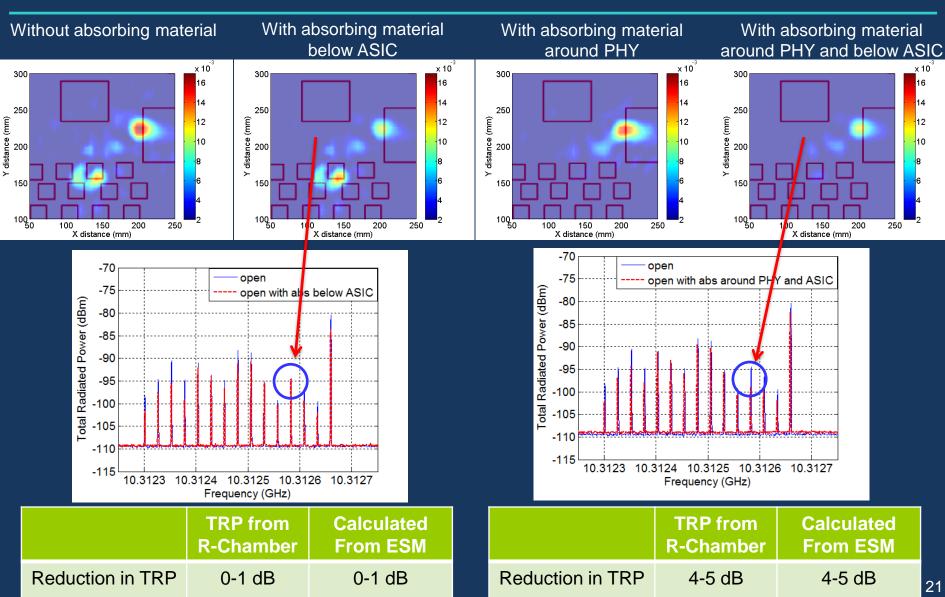


Applications of ESM





Applications of ESM





Emission Scanning: Conclusion

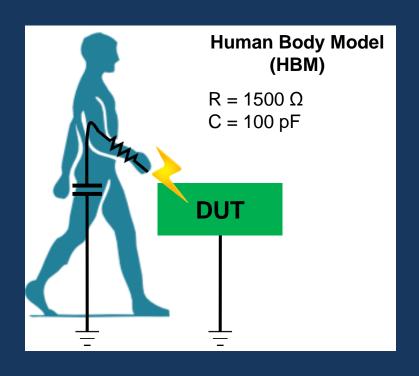
- EMI scanning is a powerful tool for identifying near-field sources.
- Measuring the phase distribution, in addition to magnitude, helps with identifying sources that contribute to far-field using ESM.
- Near-field to far-field transformation and total radiated power estimation are useful applications of phase measurement.

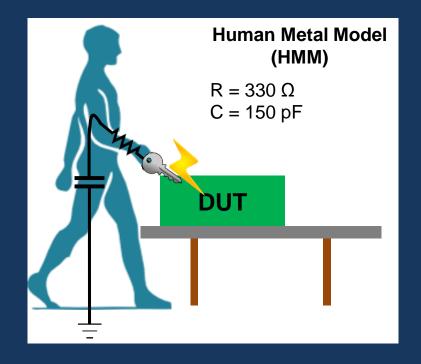


ESD Susceptibility Scanning



Electrostatic Discharge (ESD)

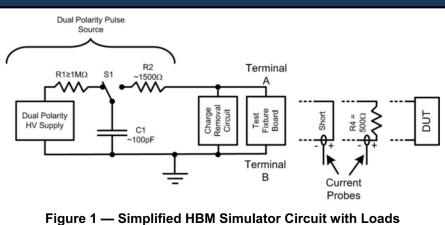


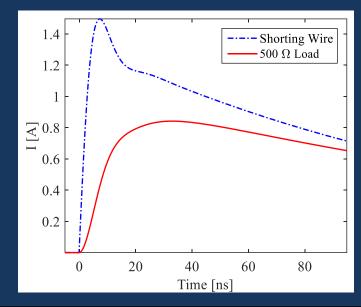


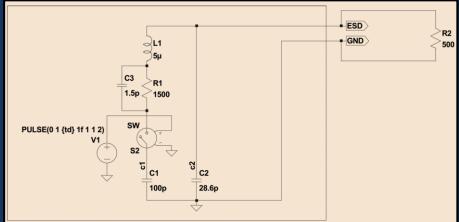


HBM Waveform









^{*} ANSI/ESDA/JEDEC JS-001-2010, MIL-STD-883J Method 3015.9

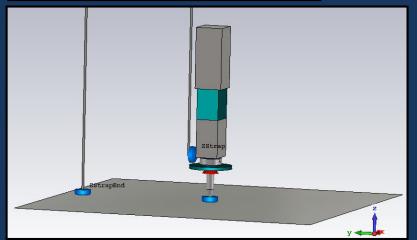
^{**} https://www.thermofisher.com/order/catalog/product/CUSPID0000019

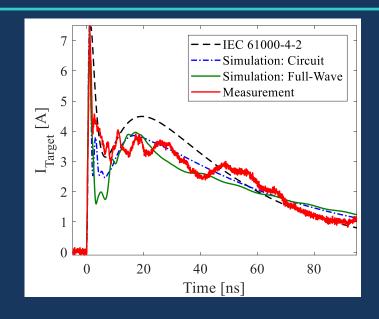


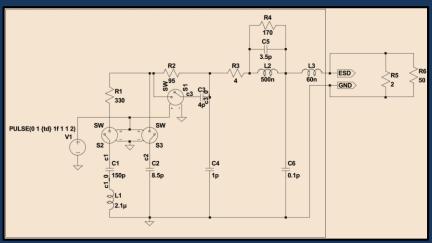
HMM Waveform



$$I(t) = \frac{I_1}{k_1} \cdot \frac{\left(\frac{t}{\tau_1}\right)^n}{1 + \left(\frac{t}{\tau_1}\right)^n} \cdot e^{\left(\frac{-t}{\tau_2}\right)} + \frac{I_2}{k_2} \cdot \frac{\left(\frac{t}{\tau_3}\right)^n}{1 + \left(\frac{t}{\tau_3}\right)^n} \cdot e^{\left(\frac{-t}{\tau_4}\right)}$$

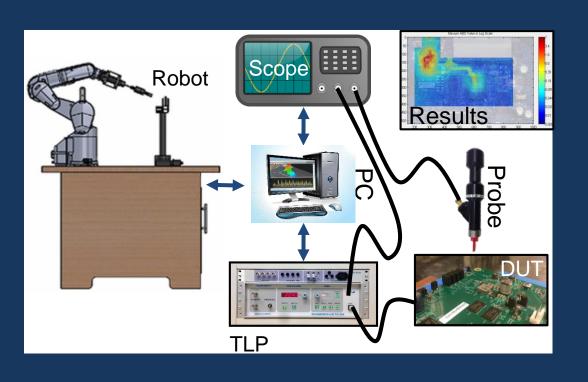


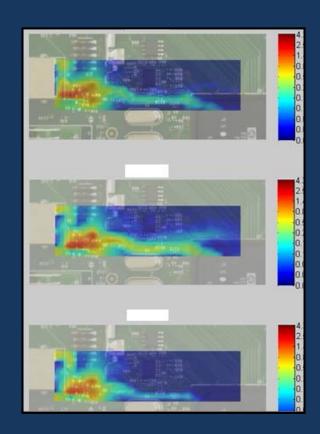






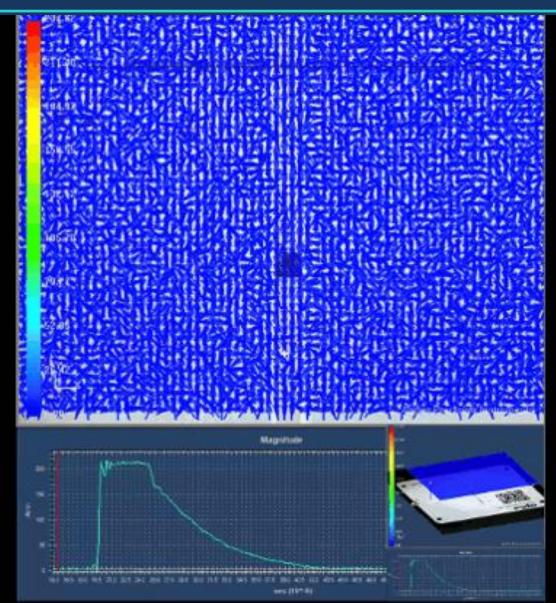
ESD Current Spreading Scanning





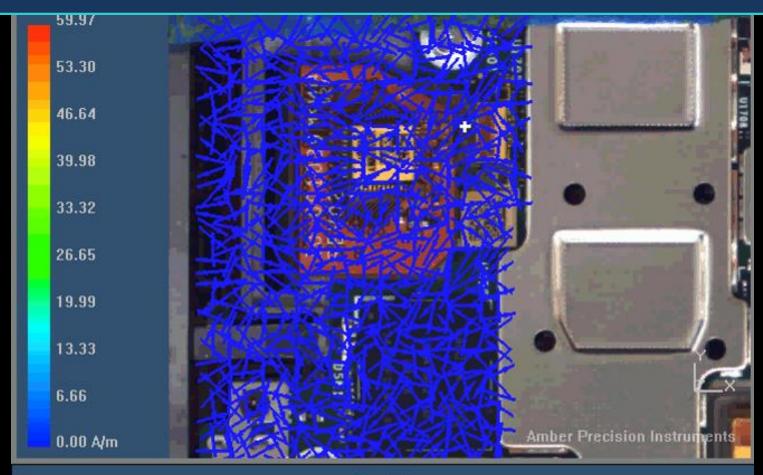


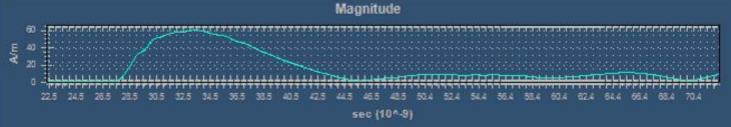
Current Spreading on Microstrip





Current Spreading on Flex PCB







ANSI/ESD SP14.5-2015

From ESDA:

For Electrostatic Discharge Sensitivity Testing – Near-Field Immunity Scanning -Component/Module/PCB Level

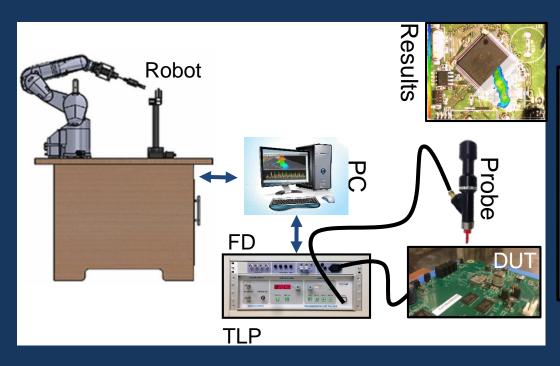
> An American National Standard Approved September 14, 2015

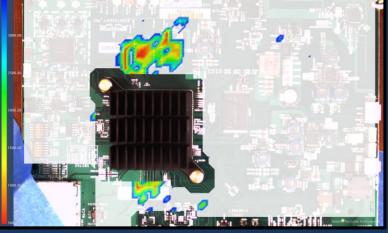


ESD scanning technology is widely accepted as a powerful tool for root cause analysis and screening high immunity components, modules and systems



ESD Immunity Scanning





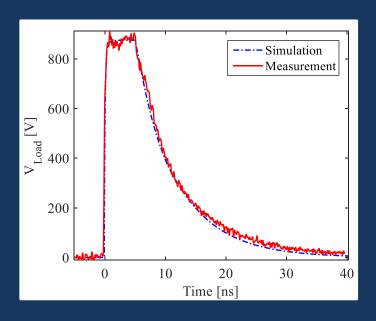
* ANSI/ESD SP14.5-2015 31



TLP Waveform





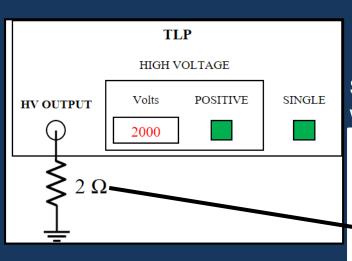


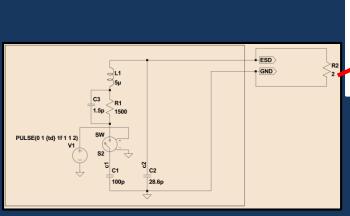
$$V_{TLP} = 2 \text{ kV}$$

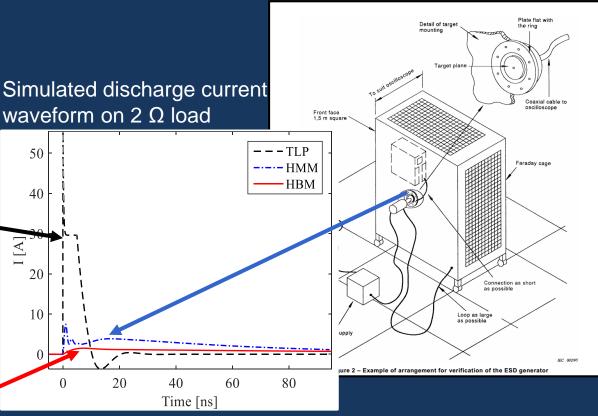
 $T_r = 500 \text{ ps}$
 $T_f = 33 \text{ ns}$



Current Waveforms: HBM vs HMM vs TLP



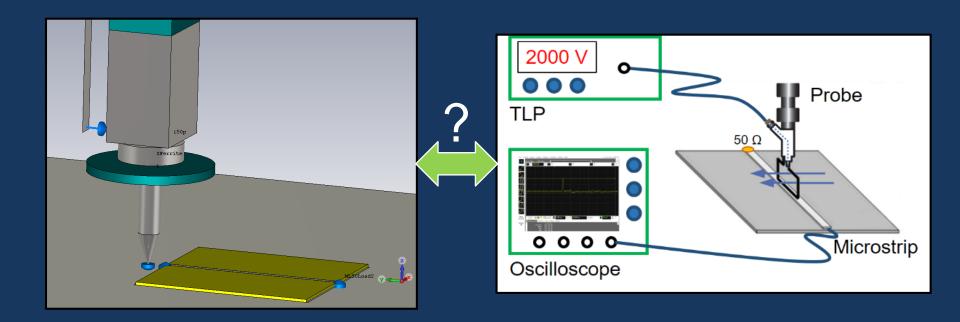




* IEC 61000-4-2



HMM vs ANSI/ESD SP14.5-2015 Simple Structure



50 ohms microstrip (3 mm wide trace)

Board dimension: 100 x 100 mm²

Board elevation from HCP: 1 mm

ESD generator distance to board: 10 mm

ESD generator setting: 2 kV CD

50 ohms microstrip (3 mm wide trace)

Board dimension: 100 x 100 mm²

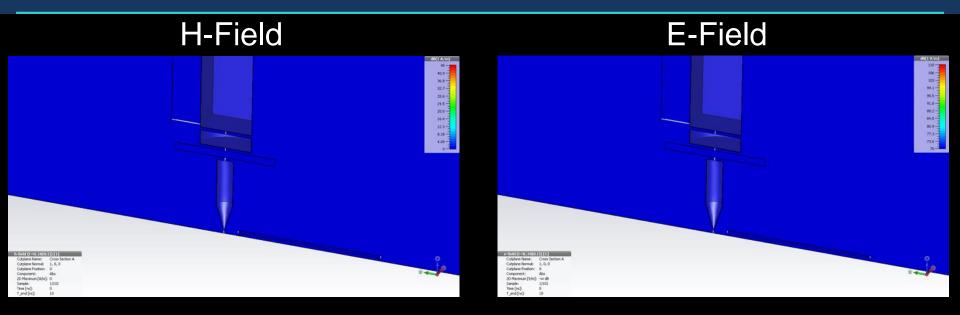
Probe: 2 mm or 5 mm loop H-field

Mechanical probe height from trace: 0 mm

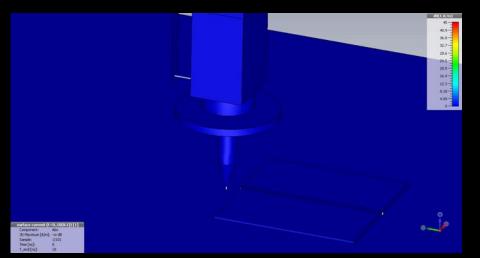
TLP setting: 2 kV



Field Coupling to Microstrip

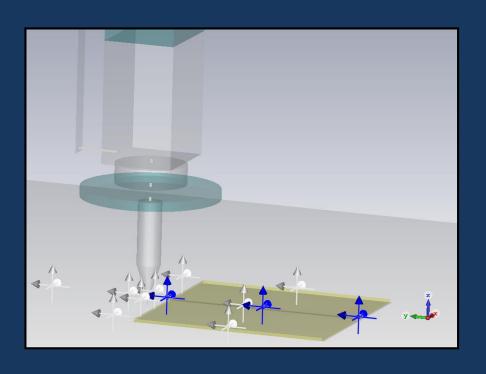


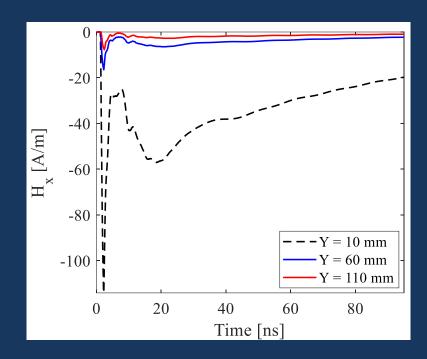
Surface Current Density





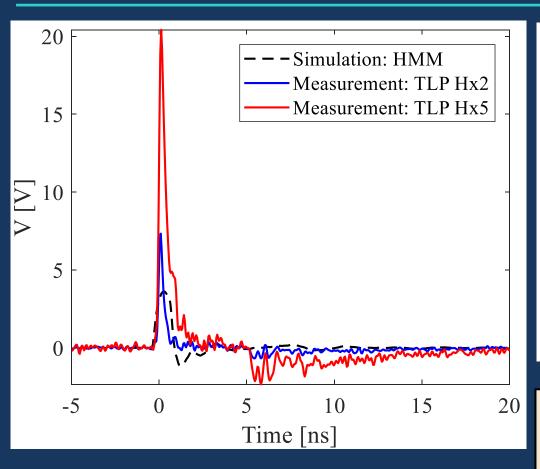
Field Attenuation from ESD

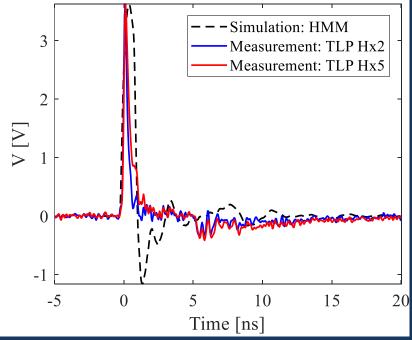






HMM vs Near-Field Injection





$$V_{eq} = \frac{1.98 \times V_{ESD}}{A_{ef}} \left(\frac{r}{2.4}\right)^{\alpha} \cdot \left(\frac{60}{R}\right)^{\beta}$$



Effect of IC Fab on ESD

White Paper 3 Part II specifically covers in detail **an overview of system ESD stress app lication methods, system diagnostic techniques to detect hard or soft failures, and the application of tools for susceptibility scanning**. For example, as illustrated in Figure 2, these types of advanced tools can be used to differentiate the characteristics of products and enable proper system protection methodology*.

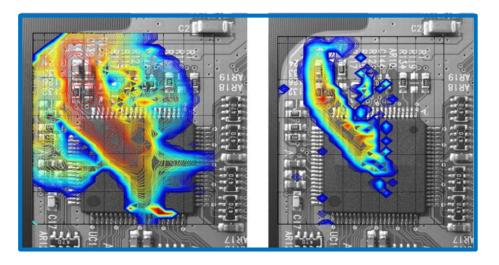


Figure 2: Susceptibility scanning using pulse techniques on Product A (left) and Product B (right)

(Courtesy of Amber Precision Instruments)

^{*} Quote from the ESDA White paper 3, Part II, page 18.

^{**} Product A and Product B are functionally identical ICs from different vendors.



Susceptibility Scanning: Conclusion

- Conducted susceptibility to an ESD even can be analyzed by measuring and visualizing scanned surface current density on the DUT.
- Susceptibility to near-field effects of an ESD event can be emulated with near-field injection.
- Near-field injection per ANSI/ESD SP14.5-2015 reproduces same failures as IEC 61000-4-2.



Thank You!

Questions?

Contact us:

amberpi@amberpi.com www.amberpi.com



References

- Application of Emission Source Microscopy Technique to EMI Source Localization above 5 GHz [Link]
- Emission Source Microscopy Technique for EMI Source Localization [Link]
- EMI Mitigation with Lossy Material at 10 GHz [Link]
- Compressed Sensing for SAR-Based Wideband Three-Dimensional Microwave Imaging System Using Non-Uniform Fast Fourier Transform [Link]
- Introduction to Fourier Optics [Link]
- Synthetic Aperture Radar Signal Processing with MATLAB Algorithms [Link]
- Wikipedia: Synthetic Aperture Radar [Link]